0.80mm (.031") Pitch SFP Stacked Multi-Port Connectors

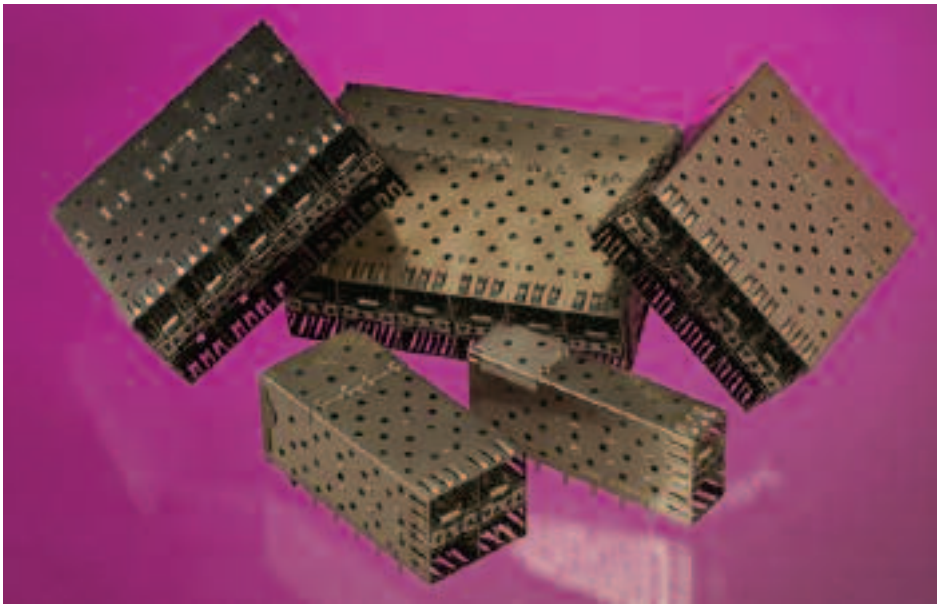
75310, 75786, 75460, 75787, 75462, 75640, 75759, 75714, 75454, 75450, 75733, 75734, 75477, 75451

Upgrade to high-speed Ethernet and Fibre Channel ports with Molex's Stacked Multi-Port SFP Connectors

Molex is rapidly expanding its Small Form-factor Pluggable (SFP) product offering to meet the demands of networking and storage industries, which require denser and faster packaging for high-speed serial interfaces. The new SFP Stacked Multi-Port Connectors are the latest additions to Molex's extensive SFP product line.

These new connectors offer high port density with complete integration of stacked 20-circuit SFP connector ports within a cage. Integrated lightpipes are available to provide port-status indication to the user. The product line encompasses connectors offered in two heights and is available in five port configurations: 2-by-1, 2-by-2, 2-by-4, 2-by-5 and 2-by-6.

Molex's SFP Stacked Multi-Port Connectors accept SFP MSA-compliant modules, allowing installers to configure and upgrade high-speed Ethernet and Fibre Channel (FC) ports. Tin/Lead press-fit connector tails are provided as the standard option. Tin-plated tails will also be available to meet lead-free requirements. Contact Molex for additional information.



Multi-port connectors with lightpipes

Features and Benefits

- High-speed contact design meets 4.25Gbps SFP requirements and is capable of speeds up to 10Gbps
- Connectors are available in multiple port configurations (2, 4, 8, 10 and 12) providing greater port density and reduced PCB assembly labor
- Integrated lightpipe option, for use with mono or bi-color SMT LED's provides port status and activity feedback
- Modules are oriented "belly-to-belly" when inserted assuring ease of module removal from the port
- Connectors are available in 2 heights: medium 25.50mm (1.000") and tall 29.30mm (1.150"); Medium-height connectors meet industry standard and are consistent with the stacked multi-port modular jack design; Tall-height connector (2-by-1 only) is designed for 1U applications

SPECIFICATIONS

Reference Information

Packaging: Tray
UL File No.: E29179
CSA File No.: LR19980
Mates With: SFP MSA-compliant modules
Designed In: Millimeters

Electrical

Voltage: 120V
Current: 0.5A max.
Dielectric Withstanding Voltage: 300V
Insulation Resistance: 1 Megohm

Mechanical

Insertion Force to PCB: 35.59N (8 lb) per compliant pin, max.
Mating Force: 40N (8.99 lb) max.
Unmating Force: 11.5N (2.59 lb) max.
Durability: 100 cycles

Physical

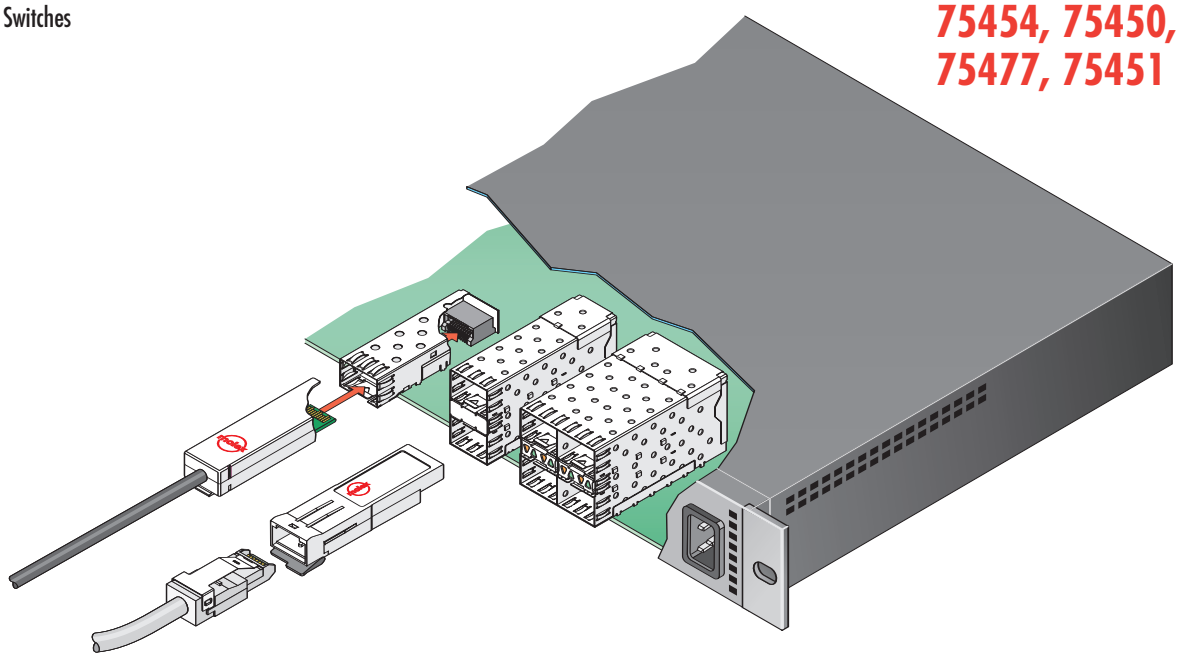
Housing: High-temperature plastic, Glass-filled
Contact: Tin/Brass (Sn/CuZn)
Plating:
Contact Area — Gold (Au)
Solder Tail Area — Tin/Lead (Sn/Pb) or Tin (Sn)
Underplating — Nickel (Ni)
PCB Thickness: 2.36mm (0.093")
Operating Temperature: -40 to +85°C

APPLICATIONS

0.80mm (.031") Pitch SFP Stacked Multi-Port Connectors

75310, 75786, 75460, 75787, 75462, 75640, 75759, 75714, 75454, 75450, 75733, 75734, 75477, 75451

- Networking, Storage and Telecommunication
  - Hubs
  - Routers
  - Servers
  - Switches



ORDERING INFORMATION

Order No.	Port Configuration	Height	Mounting	Lightpipes	EMI Protection
75310-0001	2-by-1	29.30mm (1.150")	Through-hole	Yes	Gasket with flange
75786-0001			Press-fit		
75460-0001			Through-hole		Gasket with extended flange
75787-0001			Press-fit		
75462-0001		25.50mm (1.000")		No	Spring fingers
75640-0001				Yes	
75759-0001	2-by-2			No	
75714-0001				Yes	
75454-0001	2-by-4			No	
75450-0001				Yes	
75733-0001	2-by-5			No	
75734-0001				Yes	
75477-0001	2-by-6			No	
75451-0001				Yes	

Americas Headquarters
Lisle, Illinois 60532 U.S.A.
1-800-78MOLEX
amerinfo@molex.com

Far East North Headquarters
Yamato, Kanagawa, Japan
81-462-65-2324
feninfo@molex.com

Far East South Headquarters
Jurong, Singapore
65-6-268-6868
fesinfo@molex.com

European Headquarters
Munich, Germany
49-89-413092-0
eurinfo@molex.com

Corporate Headquarters
2222 Wellington Ct.
Lisle, IL 60532 U.S.A.
630-969-4550
Fax:630-969-1352

Visit our Web site at http://www.molex.com/product/SFP_Stacked_Connectors

Order No. USA-321

Printed in USA/JI/2005.08

©2005 Molex